

Single Inverter Gate

Check for Samples: [SN74LVC1GU04](#)

FEATURES

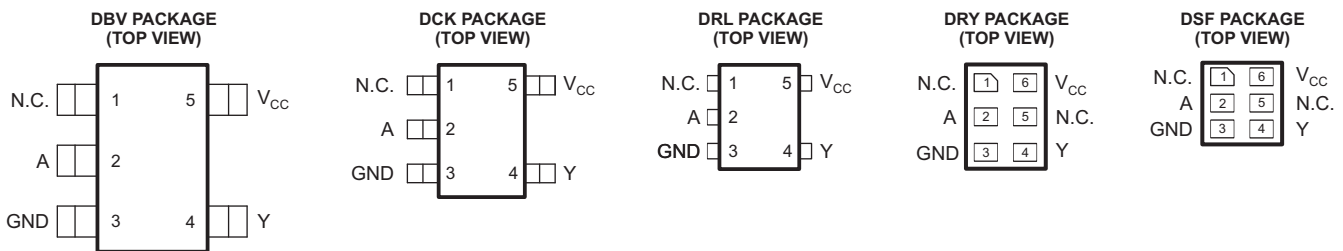
- Available in the Texas Instruments NanoFree™ Package
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Unbuffered Output
- Max t_{pd} of 3.7 ns at 3.3 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 24 -mA Output Drive at 3.3 V
- I_{off} Supports Live Insertion, Partial Power Down Mode, and Back Drive Protection
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION

This single inverter gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1GU04 contains one inverter with an unbuffered output and performs the Boolean function $Y = \bar{A}$.

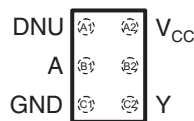
NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.



See mechanical drawings for dimensions.

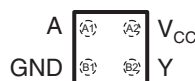
N.C. – No internal connection

YZP PACKAGE (TOP VIEW)



DNU – Do not use

YZV PACKAGE (TOP VIEW)



YZP Package Terminal Assignments

| | 1 | 2 |
|----------|-----|----------|
| A | DNU | V_{CC} |
| B | A | No ball |
| C | GND | Y |

YZV Package Terminal Assignments

| | 1 | 2 |
|----------|-----|----------|
| A | A | V_{CC} |
| B | GND | Y |



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

Function Table

| INPUT A | OUTPUT Y |
|------------|-------------|
| H | L |
| L | H |

**Logic Diagram (Positive Logic)
DBV,DSF,DRY, DCK, DRL, and YZP Package****YZV Package**

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | RATING | UNIT |
|------------------|--|-------------------------------|------|
| V _{CC} | Supply voltage range | –0.5 to 6.5 | V |
| V _I | Input voltage range ⁽²⁾ | 0.5 to 6.5 | V |
| V _O | Voltage range applied to any output in the high or low state ⁽²⁾ ⁽³⁾ | –0.5 to V _{CC} + 0.5 | V |
| I _{IK} | Input clamp current | V _I < 0 | –50 |
| I _{OK} | Output clamp current | V _O < 0 | –50 |
| I _O | Continuous output current | ±50 | mA |
| | Continuous current through V _{CC} or GND | ±100 | mA |
| θ _{JA} | Package thermal impedance ⁽⁴⁾ | DBV package | 206 |
| | | DCK package | 252 |
| | | DRL package | 142 |
| | | YZP package | 132 |
| | | YZV package | 116 |
| | | DSF package | 300 |
| | | DRY package | 234 |
| T _{stg} | Storage temperature range | –65 to 150 | °C |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

| | | MIN | MAX | UNIT |
|-----------------|--------------------------------|--------------------------|------------------------|------|
| V _{CC} | Supply voltage | 1.65 | 5.5 | V |
| V _{IH} | High-level input voltage | I _O = –100 μA | 0.75 × V _{CC} | V |
| V _{IL} | Low-level input voltage | I _O = 100 μA | 0.25 × V _{CC} | V |
| V _I | Input voltage | 0 | 5.5 | V |
| V _O | Output voltage | 0 | V _{CC} | V |
| I _{OH} | High-level output current | V _{CC} = 1.65 V | –4 | mA |
| | | V _{CC} = 2.3 V | –8 | |
| | | V _{CC} = 3 V | –16 | |
| | | V _{CC} = 4.5 V | –24 | |
| I _{OL} | Low-level output current | V _{CC} = 1.65 V | 4 | mA |
| | | V _{CC} = 2.3 V | 8 | |
| | | V _{CC} = 3 V | 16 | |
| | | V _{CC} = 4.5 V | 24 | |
| T _A | Operating free-air temperature | –40 | 125 | °C |

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | V _{CC} | –40°C to 85°C | | | –40°C to 125°C | | | UNIT |
|-----------------|-----------------------------------|---|-----------------|-----------------------|--------------------|-----|-----------------------|--------------------|-----|------|
| | | | | MIN | TYP ⁽¹⁾ | MAX | MIN | TYP ⁽¹⁾ | MAX | |
| V _{OH} | V _{IL} = 0 V | I _{OH} = –100 μA | 1.65 V to 5.5 V | V _{CC} – 0.1 | | | V _{CC} – 0.1 | | | V |
| | | I _{OH} = –4 mA | 1.65 V | 1.2 | | | 1.2 | | | |
| | | I _{OH} = –8 mA | 2.3 V | 1.9 | | | 1.9 | | | |
| | | I _{OH} = –16 mA | 3 V | 2.4 | | | 2.4 | | | |
| | | I _{OH} = –24 mA | | 2.3 | | | 2.3 | | | |
| | | I _{OH} = –32 mA | 4.5 V | 3.8 | | | 3.8 | | | |
| V _{OL} | V _{IH} = V _{CC} | I _{OL} = 100 μA | 1.65 V to 5.5 V | | | | 0.1 | | | V |
| | | I _{OL} = 4 mA | 1.65 V | | | | 0.45 | | | |
| | | I _{OL} = 8 mA | 2.3 V | | | | 0.3 | | | |
| | | I _{OL} = 16 mA | 3 V | | | | 0.4 | | | |
| | | I _{OL} = 24 mA | | | | | 0.55 | | | |
| | | I _{OL} = 32 mA | 4.5 V | | | | 0.55 | | | |
| I _I | A input | V _I = 5.5 V or GND | 0 to 5.5 V | | | | ±5 | | | μA |
| I _{CC} | | V _I = 5.5 V or GND, I _O = 0 | 1.65 V to 5.5 V | | | | 10 | | | μA |
| C _i | | V _I = V _{CC} or GND | 3.3 V | 7 | | | | | | pF |

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (See Figure 1)

| PARAMETER | FROM (INPUT) | TO (INPUT) | SN74LVC1GU04 –40°C to 85°C | | | | | | | | UNIT |
|-----------------|--------------|------------|------------------------------------|-----|-----------------------------------|-----|-----------------------------------|-----|---------------------------------|-----|------|
| | | | V _{CC} = 1.8 V ±0.15 V | | V _{CC} = 2.5 V ±0.2 V | | V _{CC} = 3.3 V ±0.3 V | | V _{CC} = 5 V ±0.5 V | | |
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | 1.3 | 5 | 1 | 4 | 1.1 | 3.7 | 1 | 3 | ns |

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (See Figure 1)

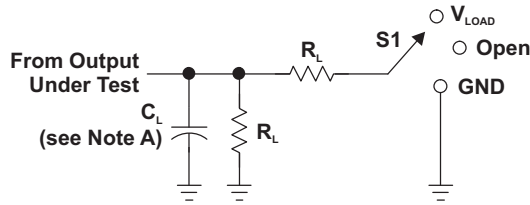
| PARAMETER | FROM (INPUT) | TO (INPUT) | SN74LVC1GU04 –40°C to 125°C | | | | | | | | UNIT |
|-----------------|--------------|------------|------------------------------------|-----|-----------------------------------|-----|-----------------------------------|-----|---------------------------------|-----|------|
| | | | V _{CC} = 1.8 V ±0.15 V | | V _{CC} = 2.5 V ±0.2 V | | V _{CC} = 3.3 V ±0.3 V | | V _{CC} = 5 V ±0.5 V | | |
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | 1.3 | 5.5 | 1 | 4.5 | 1.1 | 4.2 | 1 | 3.5 | ns |

Operating Characteristics

T_A = 25°C

| PARAMETER | TEST CONDITIONS | V _{CC} = 1.8 V | V _{CC} = 2.5 V | V _{CC} = 3.3 V | V _{CC} = 5 V | UNIT | |
|-----------------|-------------------------------|-------------------------|-------------------------|-------------------------|-----------------------|------|----|
| | | TYP | TYP | TYP | TYP | | |
| C _{pd} | Power dissipation capacitance | f = 10 MHz | 9 | 11 | 13 | 27 | pF |

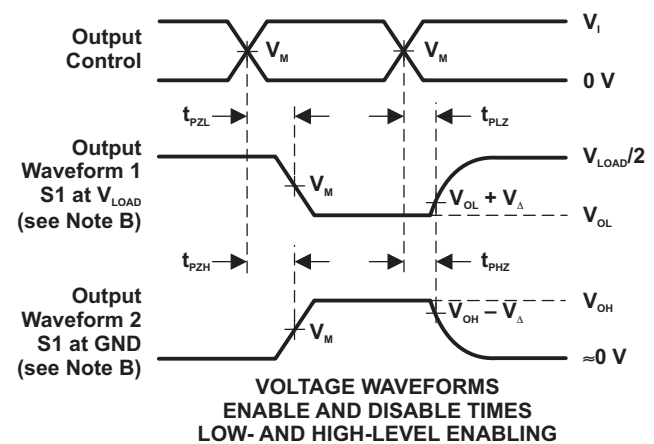
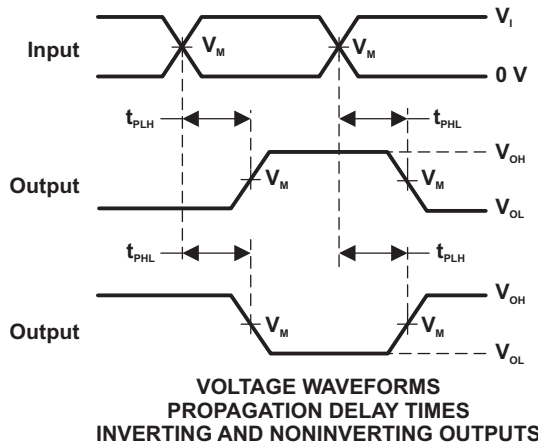
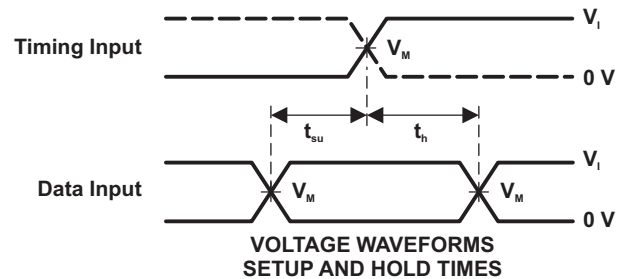
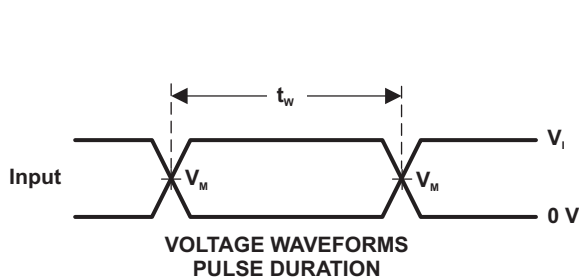
Parameter Measurement Information



LOAD CIRCUIT

| TEST | S1 |
|-------------------|------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | V_{LOAD} |
| t_{PHZ}/t_{PZH} | GND |

| V_{CC} | INPUTS | | V_M | V_{LOAD} | C_L | R_L | V_{Δ} |
|----------------------------------|----------|----------------------|------------|-------------------|-------|--------------|--------------|
| | V_I | t_r/t_f | | | | | |
| $1.8\text{ V} \pm 0.15\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 k Ω | 0.15 V |
| $2.5\text{ V} \pm 0.2\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| $3.3\text{ V} \pm 0.3\text{ V}$ | 3 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| $5\text{ V} \pm 0.5\text{ V}$ | V_{CC} | $\leq 2.5\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 50 pF | 500 Ω | 0.3 V |



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_o = 50\ \Omega$.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 H. All parameters and waveforms are not applicable to all devices.




Figure 1. Load Circuit and Voltage Waveforms

REVISION HISTORY

| Changes from Revision U (June 2011) to Revision V | Page |
|--|------|
| • Updated document to new TI data sheet format. | 1 |
| • Updated operating temperature range. | 3 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|------------------------------------|-------------------------|
| 74LVC1GU04DBVRE4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CU42 ~ CU45 ~ CU4F ~ CU4R ~ CU4T) | Samples |
| 74LVC1GU04DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CU42 ~ CU45 ~ CU4F ~ CU4R ~ CU4T) | Samples |
| 74LVC1GU04DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CU45 ~ CU4F ~ CU4R) | Samples |
| 74LVC1GU04DCKRE4 | ACTIVE | SC70 | DCK | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CD5 ~ CDF ~ CDK ~ CDR ~ CDT) | Samples |
| 74LVC1GU04DCKRG4 | ACTIVE | SC70 | DCK | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CD5 ~ CDF ~ CDK ~ CDR ~ CDT) | Samples |
| 74LVC1GU04DCKTE4 | ACTIVE | SC70 | DCK | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CD5 ~ CDF ~ CDK ~ CDR ~ CDT) | Samples |
| 74LVC1GU04DCKTG4 | ACTIVE | SC70 | DCK | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CD5 ~ CDF ~ CDK ~ CDR ~ CDT) | Samples |
| 74LVC1GU04DRLRG4 | ACTIVE | SOT | DRL | 5 | 4000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CDR | Samples |
| SN74LVC1GU04DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CU42 ~ CU45 ~ CU4F ~ CU4R ~ CU4T) | Samples |
| SN74LVC1GU04DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CU45 ~ CU4F ~ CU4R) | Samples |
| SN74LVC1GU04DCKR | ACTIVE | SC70 | DCK | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CD5 ~ CDF ~ CDK ~ CDR ~ CDT) | Samples |
| SN74LVC1GU04DCKT | ACTIVE | SC70 | DCK | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CD5 ~ CDF ~ CDK ~ CDR ~ CDT) | Samples |
| SN74LVC1GU04DRLR | ACTIVE | SOT | DRL | 5 | 4000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CDR | Samples |
| SN74LVC1GU04DRY2 | ACTIVE | SON | DRY | 6 | 5000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CD | Samples |
| SN74LVC1GU04DRYR | ACTIVE | SON | DRY | 6 | 5000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CD | Samples |
| SN74LVC1GU04DSF2 | PREVIEW | SON | DSF | 6 | 5000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CD | |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|---|
| SN74LVC1GU04DSFR | ACTIVE | SON | DSF | 6 | 5000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CD |  |
| SN74LVC1GU04YZPR | ACTIVE | DSBGA | YZP | 5 | 3000 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | (CD7 ~ CDN) |  |
| SN74LVC1GU04YZVR | ACTIVE | DSBGA | YZV | 4 | 3000 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | CD (7 ~ N) |  |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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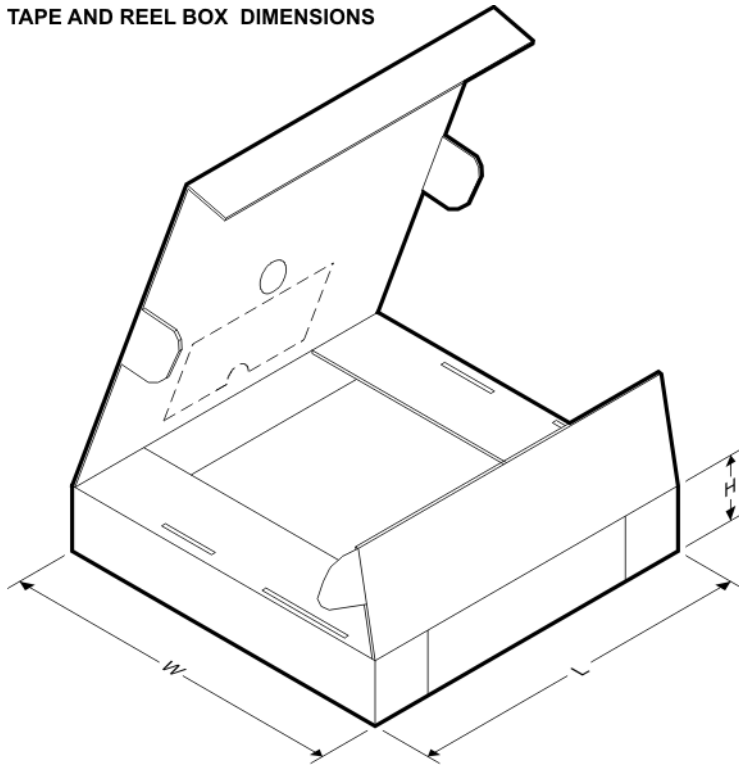
TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVC1GU04DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.2 | 3.3 | 3.2 | 1.55 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.2 | 3.3 | 3.2 | 1.55 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 8.4 | 2.47 | 2.3 | 1.25 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DCKR | SC70 | DCK | 5 | 3000 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DCKR | SC70 | DCK | 5 | 3000 | 178.0 | 9.0 | 2.4 | 2.5 | 1.2 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 9.2 | 2.3 | 2.55 | 1.2 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DCKT | SC70 | DCK | 5 | 250 | 180.0 | 9.2 | 2.3 | 2.55 | 1.2 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DCKT | SC70 | DCK | 5 | 250 | 178.0 | 9.0 | 2.4 | 2.5 | 1.2 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DCKT | SC70 | DCK | 5 | 250 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DRLR | SOT | DRL | 5 | 4000 | 180.0 | 8.4 | 1.98 | 1.78 | 0.69 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DRY2 | SON | DRY | 6 | 5000 | 180.0 | 9.5 | 1.6 | 1.15 | 0.75 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DRY2 | SON | DRY | 6 | 5000 | 180.0 | 8.4 | 1.65 | 1.2 | 0.7 | 4.0 | 8.0 | Q3 |
| SN74LVC1GU04DRYR | SON | DRY | 6 | 5000 | 180.0 | 9.5 | 1.15 | 1.6 | 0.75 | 4.0 | 8.0 | Q1 |
| SN74LVC1GU04DSFR | SON | DSF | 6 | 5000 | 180.0 | 9.5 | 1.16 | 1.16 | 0.5 | 4.0 | 8.0 | Q2 |
| SN74LVC1GU04YZPR | DSBGA | YZP | 5 | 3000 | 178.0 | 9.2 | 1.02 | 1.52 | 0.63 | 4.0 | 8.0 | Q1 |

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVC1GU04YZVR | DSBGA | YZV | 4 | 3000 | 178.0 | 9.2 | 1.0 | 1.0 | 0.63 | 4.0 | 8.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


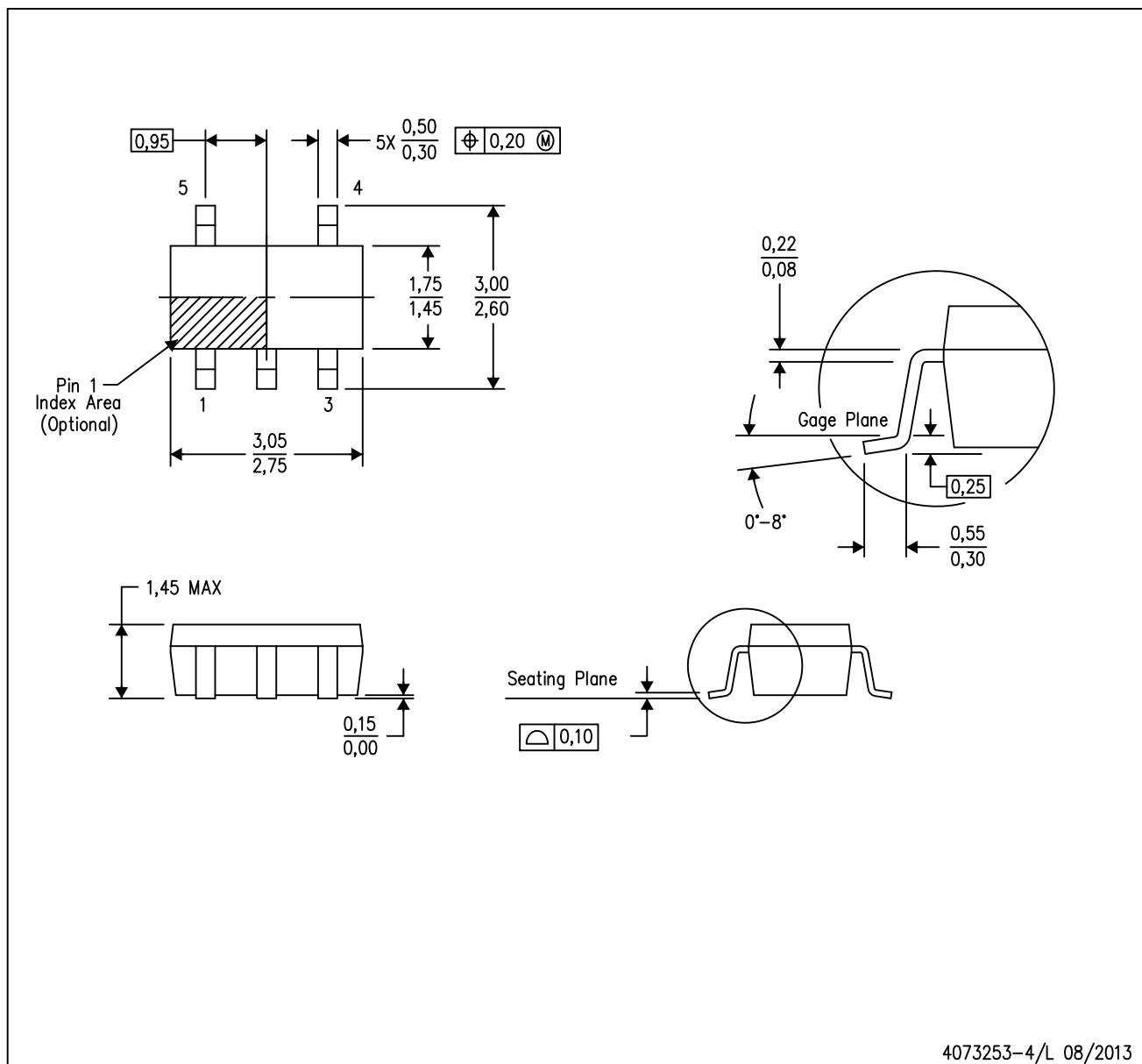
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVC1GU04DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1GU04DBVR | SOT-23 | DBV | 5 | 3000 | 202.0 | 201.0 | 28.0 |
| SN74LVC1GU04DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1GU04DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1GU04DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1GU04DCKR | SC70 | DCK | 5 | 3000 | 202.0 | 201.0 | 28.0 |
| SN74LVC1GU04DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1GU04DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1GU04DCKR | SC70 | DCK | 5 | 3000 | 205.0 | 200.0 | 33.0 |
| SN74LVC1GU04DCKT | SC70 | DCK | 5 | 250 | 205.0 | 200.0 | 33.0 |
| SN74LVC1GU04DCKT | SC70 | DCK | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1GU04DCKT | SC70 | DCK | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1GU04DRLR | SOT | DRL | 5 | 4000 | 202.0 | 201.0 | 28.0 |
| SN74LVC1GU04DRY2 | SON | DRY | 6 | 5000 | 184.0 | 184.0 | 19.0 |
| SN74LVC1GU04DRY2 | SON | DRY | 6 | 5000 | 202.0 | 201.0 | 28.0 |
| SN74LVC1GU04DRYR | SON | DRY | 6 | 5000 | 184.0 | 184.0 | 19.0 |

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVC1GU04DSFR | SON | DSF | 6 | 5000 | 184.0 | 184.0 | 19.0 |
| SN74LVC1GU04YZPR | DSBGA | YZP | 5 | 3000 | 220.0 | 220.0 | 35.0 |
| SN74LVC1GU04YZVR | DSBGA | YZV | 4 | 3000 | 220.0 | 220.0 | 35.0 |

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

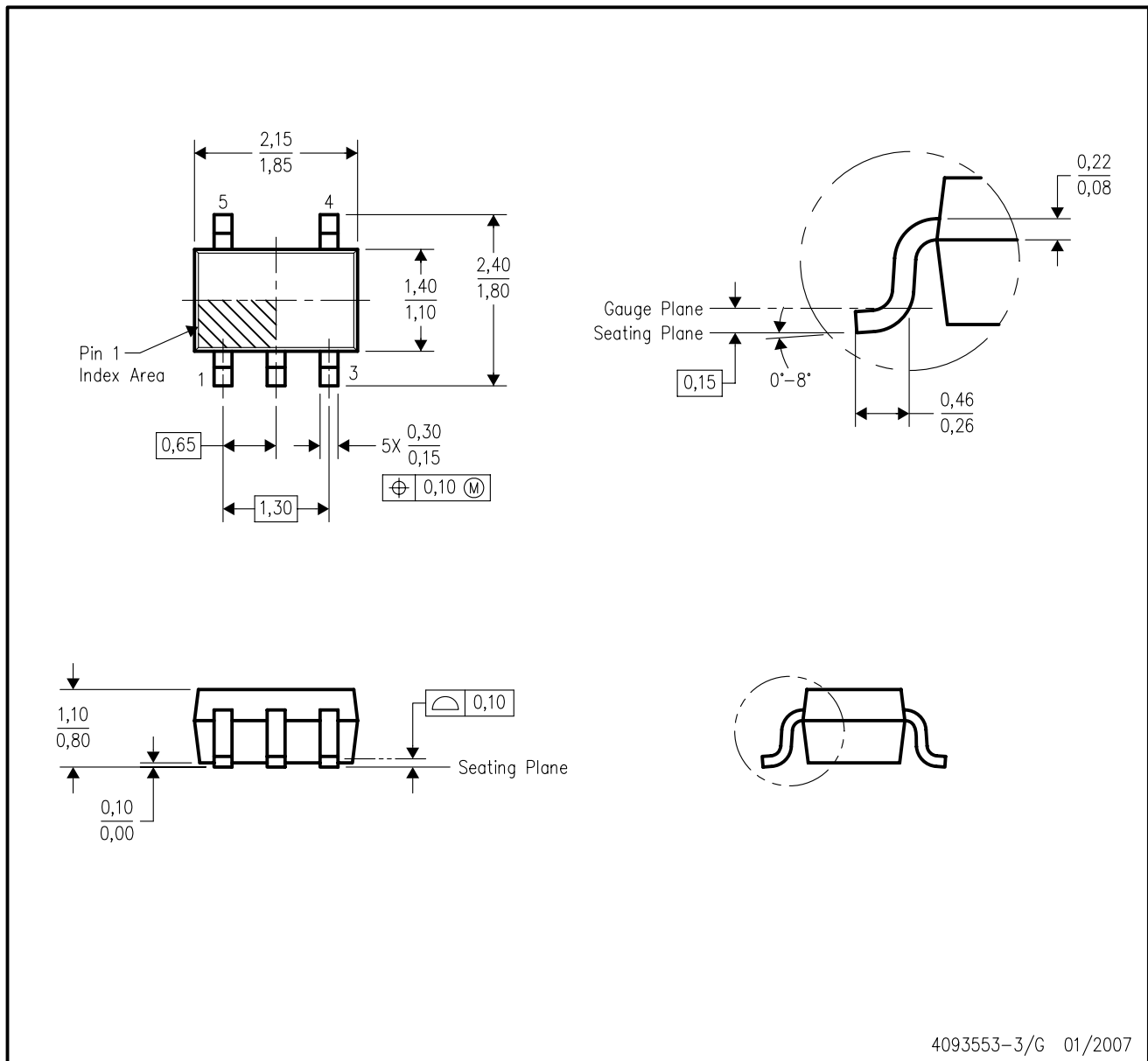
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DCK (R-PDSO-G5)

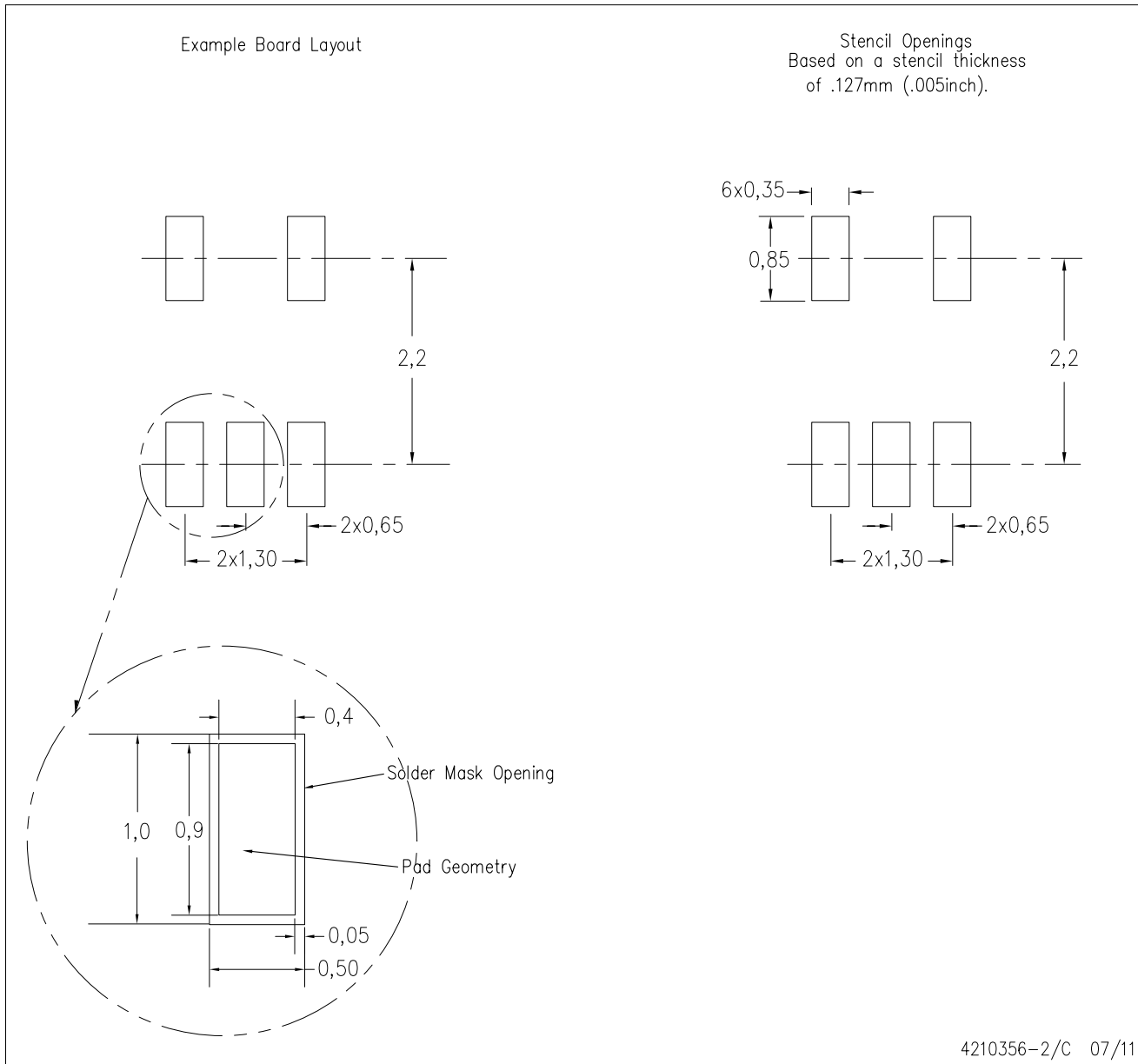
PLASTIC SMALL-OUTLINE PACKAGE



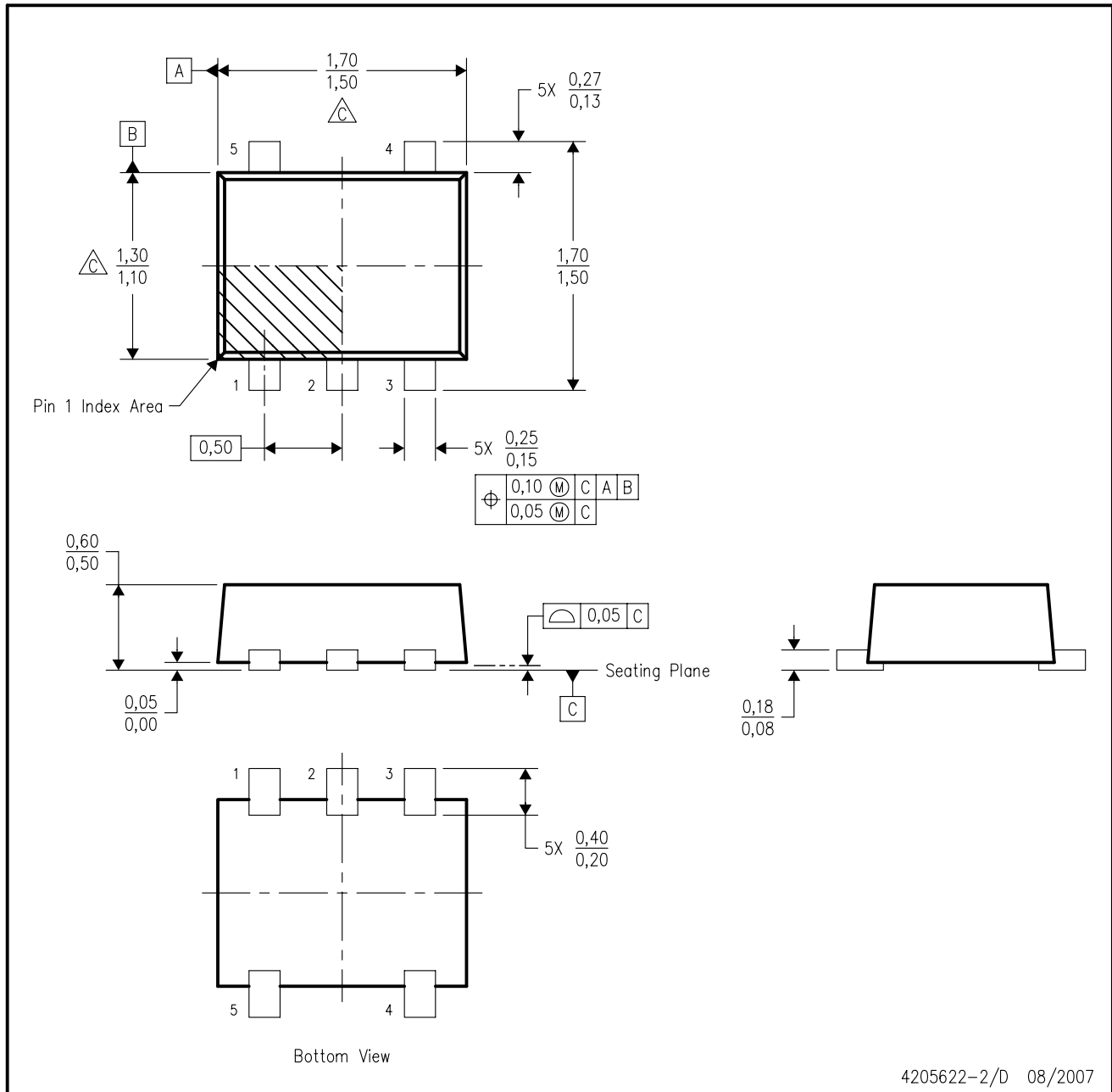
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

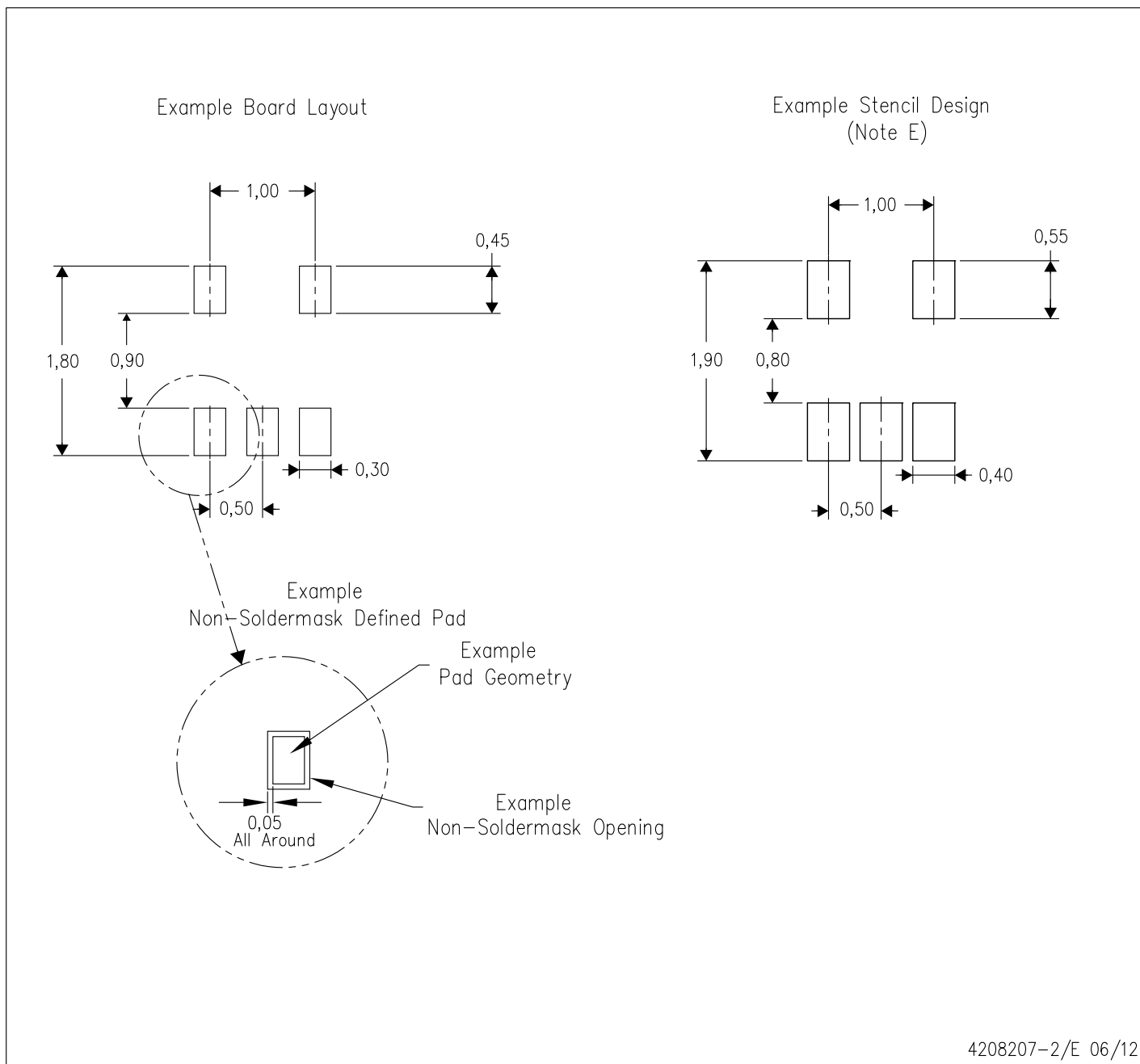
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



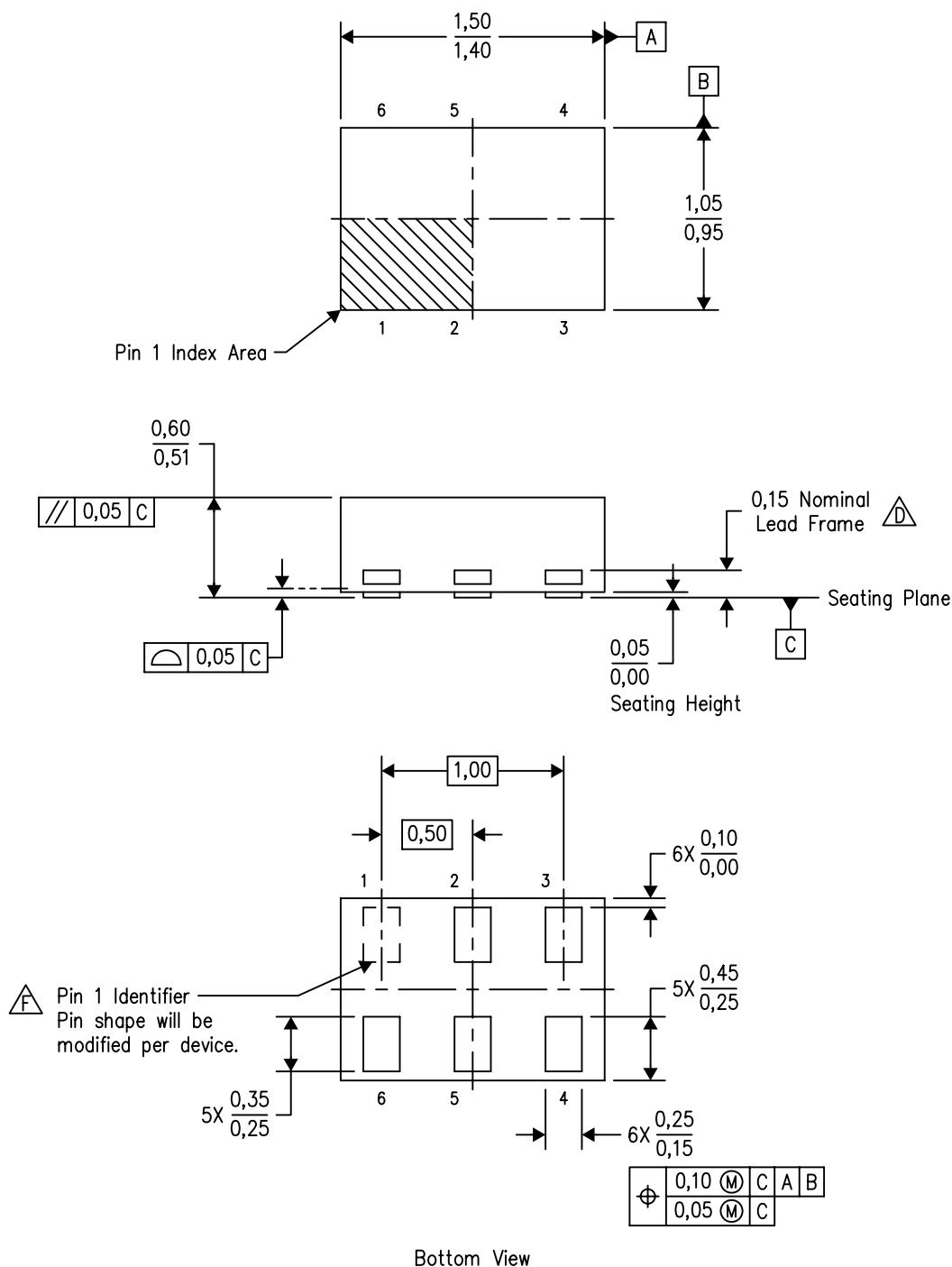
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
 - D. JEDEC package registration is pending.





- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

DRY (R-PUSON-N6)

PLASTIC SMALL OUTLINE NO-LEAD

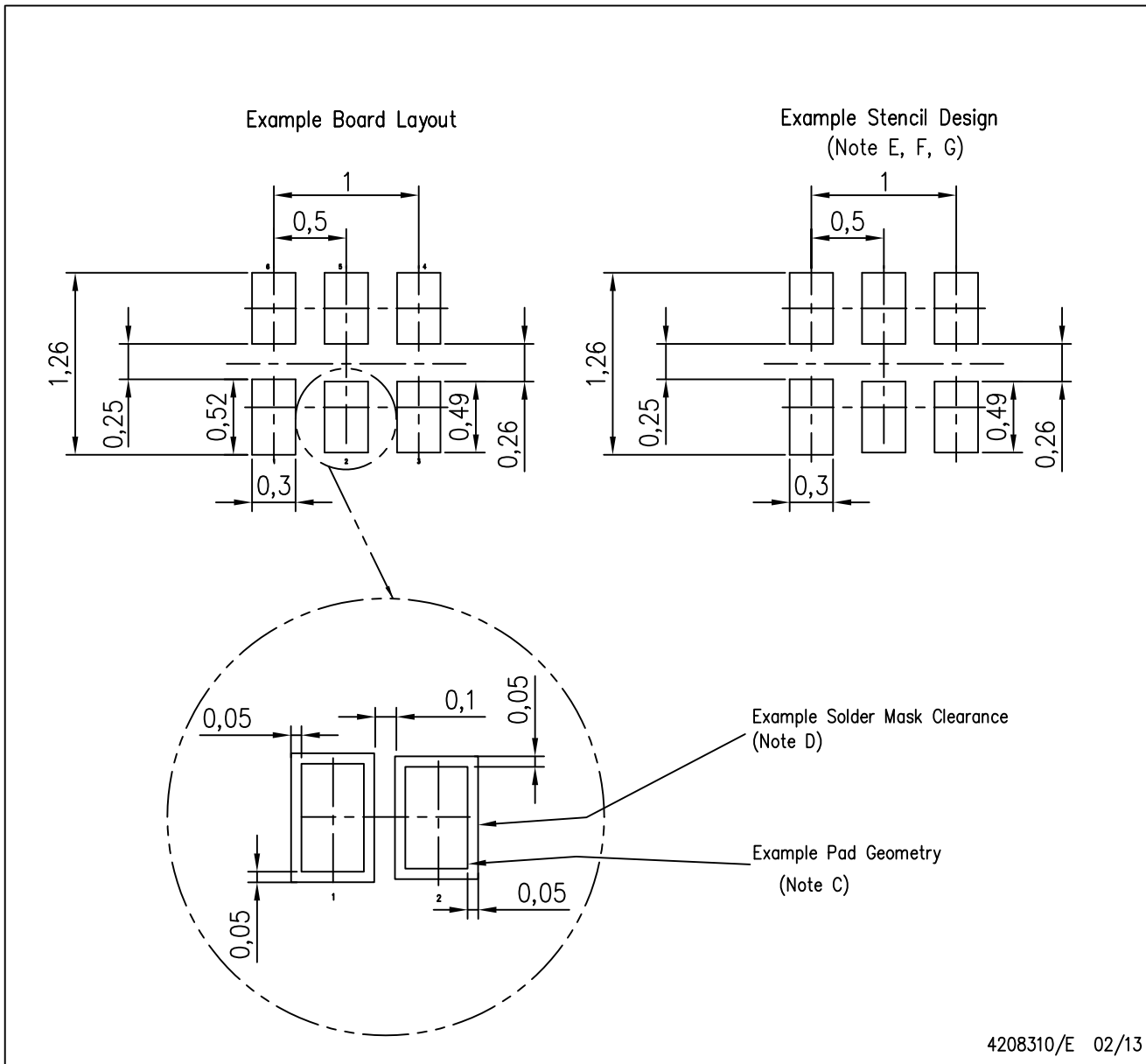


4207181/F 12/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. SON (Small Outline No-Lead) package configuration.
 -  The exposed lead frame feature on side of package may or may not be present due to alternative lead frame designs.
 - E. This package complies to JEDEC MO-287 variation UFAD.
 -  See the additional figure in the Product Data Sheet for details regarding the pin 1 identifier shape.

DRY (R-PUSON-N6)

PLASTIC SMALL OUTLINE NO-LEAD

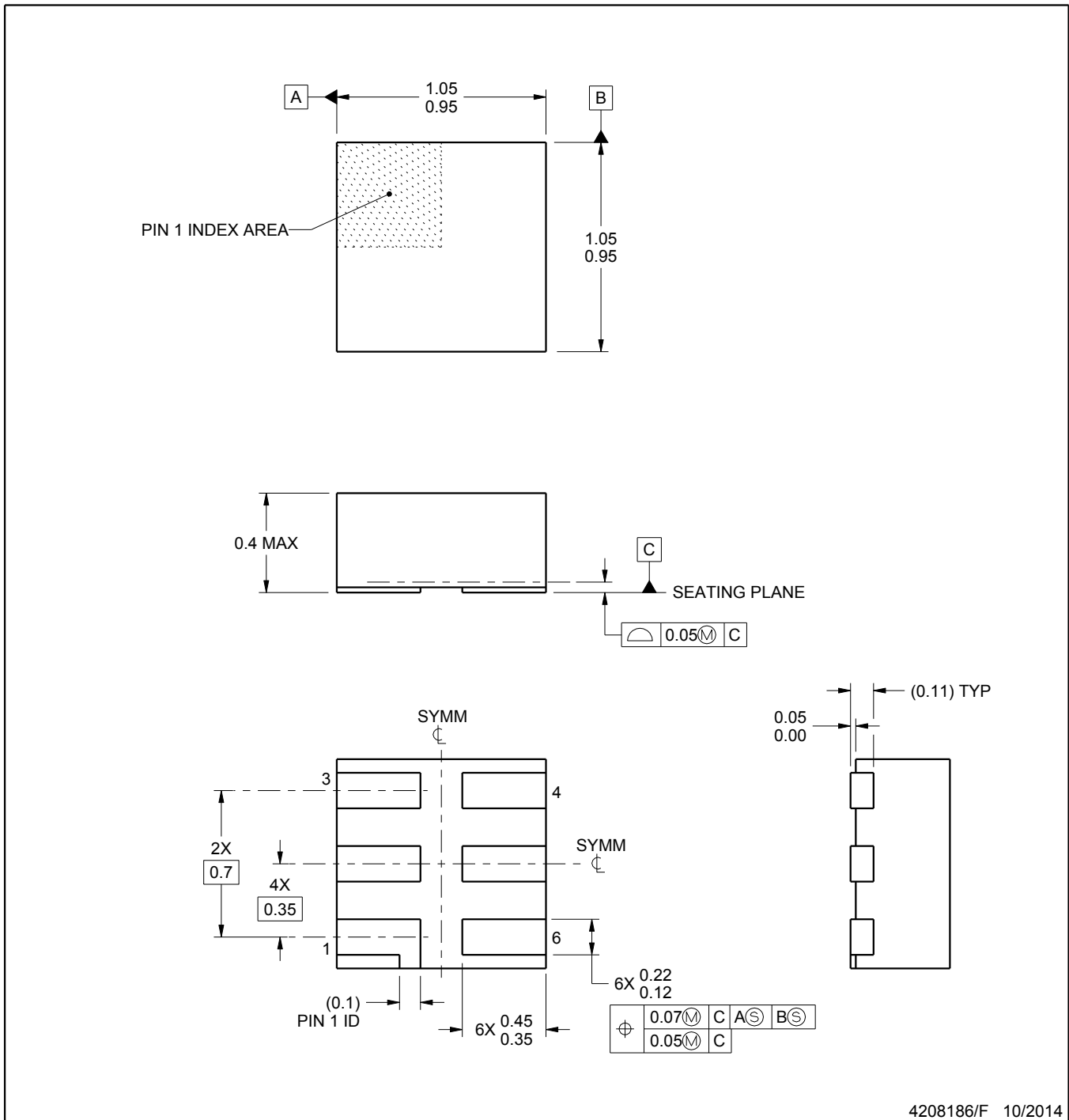


- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Side aperture dimensions over-print land for acceptable area ratio > 0.66 . Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

MECHANICAL DATA

DSF (S-PX2SON-N6)

PLASTIC SMALL OUTLINE NO-LEAD



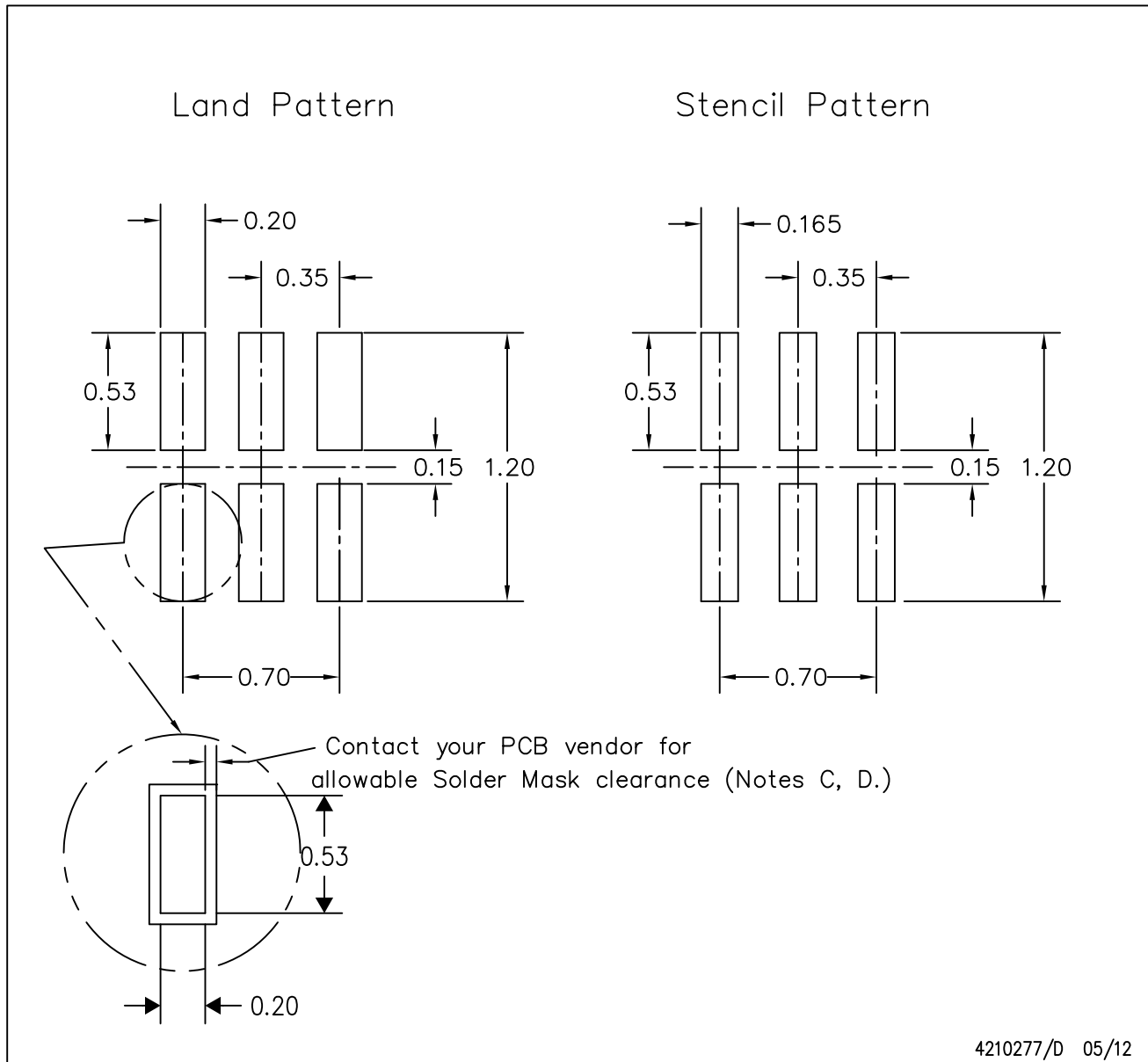
4208186/F 10/2014

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.

DSF (S-PX2SON-N6)

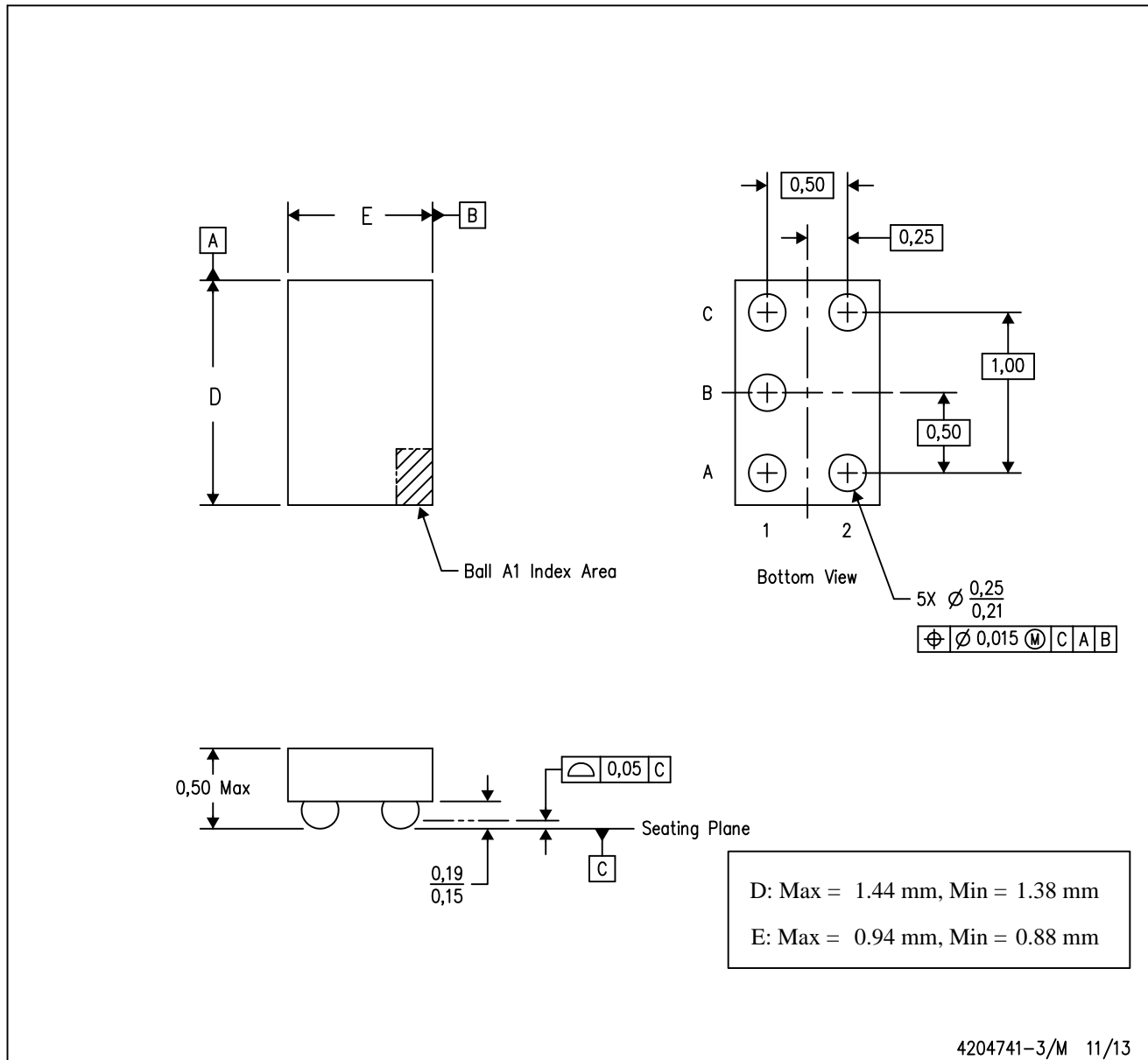
PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads. If 2 mil solder mask is outside PCB vendor capability, it is advised to omit solder mask.
 - Maximum stencil thickness 0,1016 mm (4 mils). All linear dimensions are in millimeters.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Suggest stencils cut with lasers such as Fiber Laser that produce the greatest positional accuracy.
 - Component placement force should be minimized to prevent excessive paste block deformation.

YZP (R-XBGA-N5)

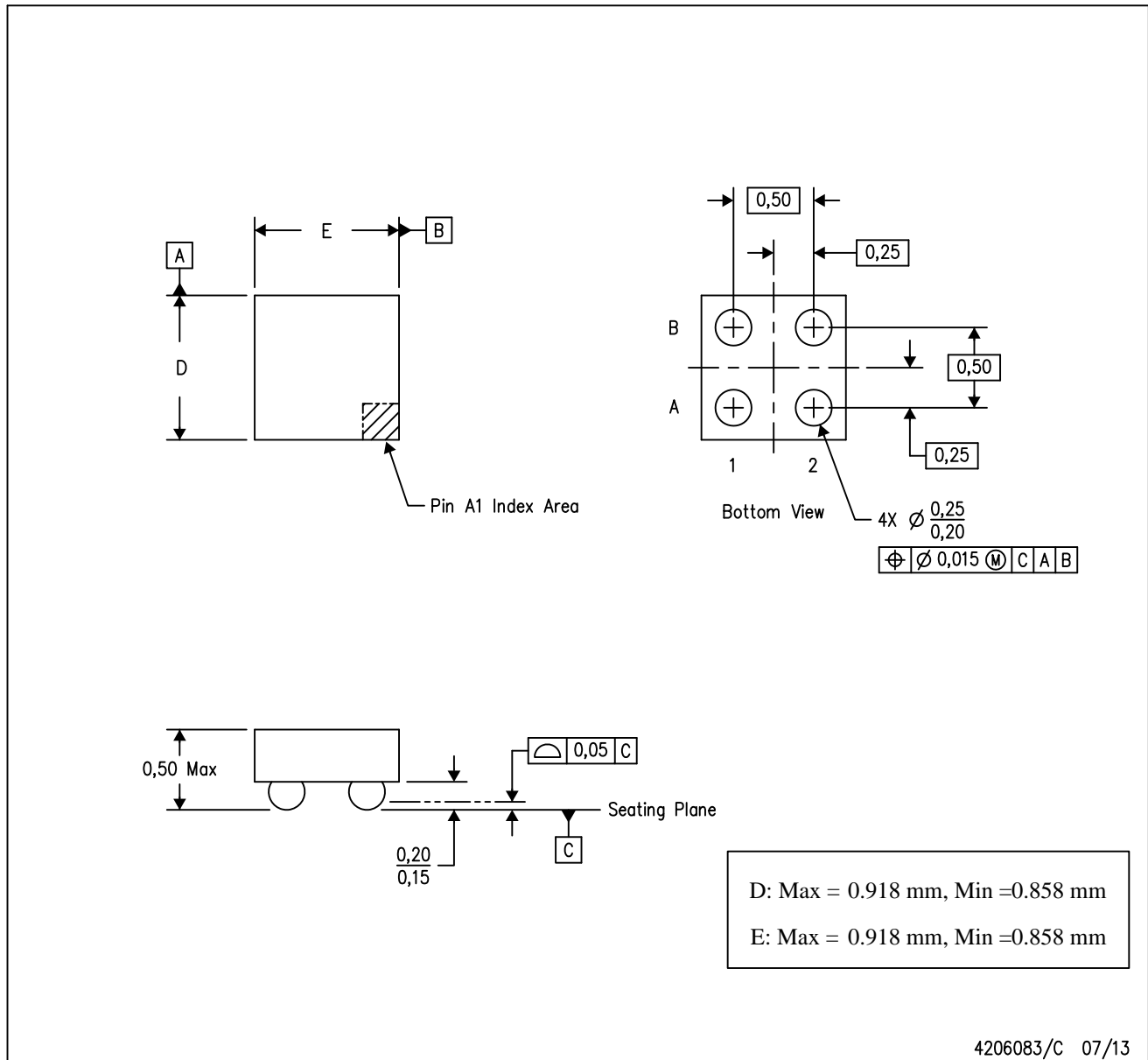
DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

YZV (S-XBGA-N4)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

NanoFree is a trademark of Texas Instruments.

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